Preferred Device

# **Surface Mount Schottky Power Rectifier**

... employing the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes, in surface mount applications where compact size and weight are critical to the system. Typical applications are ac/dc and dc-dc converters, reverse battery protection, and "Oring" of multiple supply voltages and any other application where performance and size are critical.

- Ultra Low VF
- 1st in the Market Place with a 10 V<sub>R</sub> Schottky Rectifier
- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guarding for Stress Protection

#### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Weight: 217 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 16 mm Tape and Reel, 2500 units per reel
- Polarity: Notch in Plastic Body Indicates Cathode Lead
- ESD Ratings: Machine Model = C Human Body Model = 3B
- Marking: B4L1

## **MAXIMUM RATINGS**

| Rating   | Symbol             | Value          | Unit |
|--|--------------------|----------------|------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage                         | VRRM<br>VRWM<br>VR | 10             | V    |
| Average Rectified Forward Current (@ T <sub>L</sub> = 110°C)   | lO                 | 4.0            | А    |
| Non–Repetitive Peak Surge Current<br>(Surge Applied at Rated Load Conditions<br>Halfwave, Single Phase, 60 Hz) | IFSM               | 150            | A    |
| Operating Junction Temperature   | TJ                 | -65 to<br>+125 | °C   |



## ON Semiconductor™

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# SCHOTTKY BARRIER RECTIFIERS 4.0 AMPERES 10 VOLTS



SMC CASE 403 PLASTIC

## **MARKING DIAGRAM**



Y = Year WW = Work Week B4L1 = Device Code

#### **ORDERING INFORMATION**

| Device     | Package | Shipping         |
|------------|---------|------------------|
| MBRS410LT3 | SMC     | 2500/Tape & Reel |

**Preferred** devices are recommended choices for future use and best overall value.

## THERMAL CHARACTERISTICS

| Characteristic   | Symbol                      | Min Pad<br>(Note 2) | 1 Inch Pad | Unit |
|--|-----------------------------|---------------------|------------|------|
| Thermal Resistance – Junction–to–Lead Thermal Resistance – Junction–to–Ambient | $R_{	heta JL} R_{	heta JA}$ | 12<br>109           | 7.0<br>59  | °C/W |

## **ELECTRICAL CHARACTERISTICS**

| Maximum Instantaneous Forward Voltage (Note 1)  | ٧F | T <sub>J</sub> = 25°C | T <sub>J</sub> = 100°C  | V  |
|---|----|-----------------------|-------------------------|----|
| (I <sub>F</sub> = 2.0 A)<br>(I <sub>F</sub> = 4.0 A)<br>(I <sub>F</sub> = 8.0 A)        |    | 0.31<br>0.33<br>0.35  | 0.200<br>0.225<br>0.250 |    |
| Maximum Instantaneous Reverse Current (Note 1)  | IR | T <sub>J</sub> = 25°C | T <sub>J</sub> = 100°C  | mA |
| (Rated dc Voltage, V <sub>R</sub> = 5.0 V)<br>(Rated dc Voltage, V <sub>R</sub> = 10 V) |    | 2.0<br>5.0            | 100<br>200              |    |

- 1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
- 2. Mounted with Minimum Recommended Pad Size, PC Board FR4.

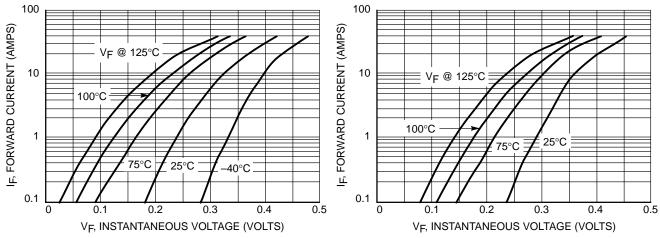
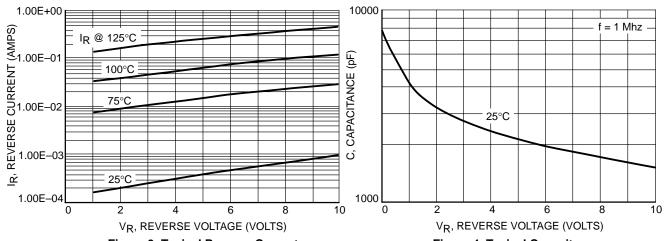


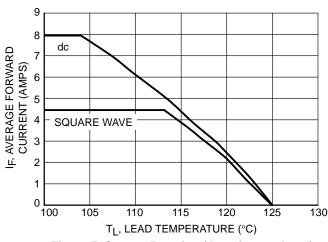
Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage



**Figure 3. Typical Reverse Current** 

Figure 4. Typical Capacitance



1.8 NOLVE 1.8 NOLVE

Figure 5. Current Derating (Junction-to-Lead)

Figure 6. Forward Power Dissipation

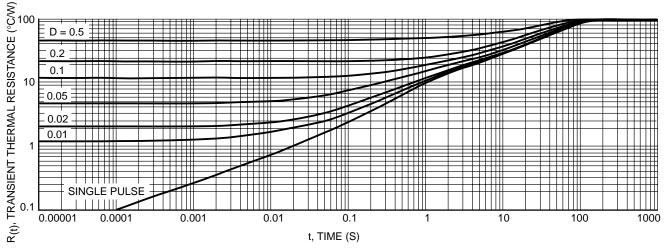


Figure 7. Thermal Response, Junction to Ambient (min pad)

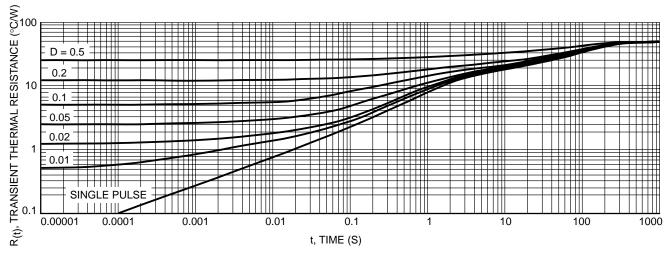
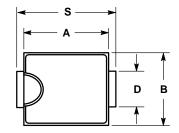


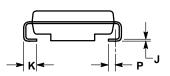
Figure 8. Thermal Response, Junction to Ambient (1 inch pad)

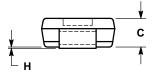
## PACKAGE DIMENSIONS

#### **SMC**

PLASTIC PACKAGE CASE 403-03 ISSUE B







#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
   Y14 5M 1982
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

|     | INCHES    |        | MILLIMETERS |       |
|-----|-----------|--------|-------------|-------|
| DIM | MIN       | MAX    | MIN         | MAX   |
| Α   | 0.260     | 0.280  | 6.60        | 7.11  |
| В   | 0.220     | 0.240  | 5.59        | 6.10  |
| С   | 0.075     | 0.095  | 1.90        | 2.41  |
| D   | 0.115     | 0.121  | 2.92        | 3.07  |
| Н   | 0.0020    | 0.0060 | 0.051       | 0.152 |
| J   | 0.006     | 0.012  | 0.15        | 0.30  |
| K   | 0.030     | 0.050  | 0.76        | 1.27  |
| Р   | 0.020 REF |        | 0.51 REF    |       |
| S   | 0.305     | 0.320  | 7.75        | 8.13  |

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